Dwg. No.: <u>H20-0433</u>

承認字號

Issued Date: 2020/3/16

Customer:	日鑫股份有限公司
(客 戶)	
Part No. (貴公司料號)	:

SPECIFICATION FOR APPROVAL

承 認 書

Description (零件名稱)	:_	V-CHIP ALUMINUM ELECTROLYTIC CAPACITORS
Lelon Series (立 隆 系 列)	:_	VUA Series
Lelon Part No).:_	VUA221M1ETR-0810

LELON ELECTRONICS CORP.

立隆電子工業股份有限公司

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Approval Signatures

貴公司承認印

Approval	Check	Design
核 准	確 認	作 成
R & D	R & D	R & D
MAR. 16. 2020	MAR. 16. 2020	MAR. 16. 2020
Jack Huang	H. Y. Huang	Z. X. Sun

Please Return One Copy with Your Approval 承 認 後 請 寄 回 本 圖 一 份 LELON ELECTRONICS CORP. Ver. 02

Part Numbering System

Product Code Guide - SMD Type

VE series	10μF	±20%	16V	Carrier Tape		4φ×5.3L	Pb-free and PET coating case	
VE-	<u>100</u>	<u>M</u>	<u>1C</u>	<u>TR</u>	-	<u>0405</u>		
1	2	3	4	5	6	7	8	9
Series	•	Capacitanc e Tolerance	Rated Voltage	Package Type	Terminal Type	Case size	Lead Wire and Coating Type	Supplement Code

1 Series:

Series is represented by a three-letter code. When the series name only has two letters, use a hyphen, "-", to fill the third blank.

2 Capacitance:

Capacitance in μF is represented by a three-digit code. The first two digits are significant and the third digit indicates the number of zeros following the significant figure. "R" represents the decimal point for capacitance under 10 μF .

Example:

_												
	Capacitance	0.1	0.47	1	4.7	10	47	100	470	1,000	4,700	10,000
	Part number	0R1	R47	010	4R7	100	470	101	471	102	472	103

3 Tolerance:

٠.	oloranoo.									
	J = -5% ~ +5%	K = -10% ~ +10%	M = -20% ~ +20%	V = -10% ~ +20%						

4 Rated voltage:

Rated voltage in volts (V) is represented by a two-digit code

•	tatoa voitago	111 701	10 (v) 10	o ropro	OOIILOC	ibyai	.vvo aig	ir ooac	<u> </u>					
	Voltage (WV)	2.5	4	6.3	10	16	20	25	35	40	50	63	80	100
	Code	0E	0G	0J	1A	1C	1D	1E	1V	1G	1H	1J	1K	2A
	Voltage (WV)	160	200	250	350	400	450							
	Code	2C	2D	2E	2V	2G	2W							

⑤ Package:

TD Dool poolsogo	
TR = Reel package	T- = Tray package for case diameter 12.5 ~ 18mm

6 Terminal:

- = No dummy terminal	K = Anti-vibration structure (30G)
A = For automotive application (10G)	G = Anti-vibration structure (50G)

(7) Case size:

The first two digits indicate case diameter and the last two digits indicate case length in mm.

						· • · · · · · · · · · · · · · · · · · ·			•• • •• • • • • • • • • • • • • • • • •	
φD×L	3x5.3	4×4.5	4×5.3	4×5.7	5×4.5	5×5.3	5×5.7	6.3×4.5	6.3×5.3	6.3×5.7
ΨΒΛΕ	0.00.0	17.1.0	17.0.0	17.0.1	OX 1.0	0.0.0	5×5.8	0.07.1.0	0.000.0	6.3×5.8
Code	0305	0404	0405	0406	0504	0505	0506	0604	0605	0606
φD×L	6.3×7.7	8×6.5	8×10	10×7.7	10×10(9.9)	10×12.5	12.5×13.5	12.5×16	16×16.5	16×21.5
Code	0607	0806	0810	1008	1010	1013	1313	1316	1616	1621
φD×L	18×16.5	18×21.5								

Note 1: When a case size is required and not shown in the table, please contact with us for further discussion.

8 Lead Wire and Coating Type:

None = Pb free wire + PET coating case (Standard design)	E = Sn-Bi wire + PET coating case
B = Sn-Bi wire + Coating case	K / L = Automotive control code

^{*} When a supplement code following a blank digit code of lead wire and case coating type (standard design), use a hyphen, "-", to fill the blank digit.

Supplement code (Optional):

For special control purpose

Note 2: The case size "5x5.8, 6.3x5.8" is for VZS series only.

^{*} When the automotive control code is required, please contact with us for further discussion.

Lelon P/N: VUA221M1ETR-0810

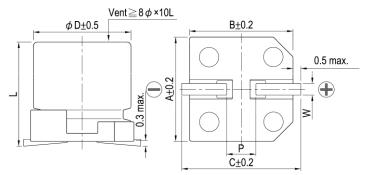
LELON ELECTRONICS CORP.

VUA 220 μ F / 25 V $- 8\phi \times 10$ L

CUSTOMER : 日鑫股份有限公司

CUSTOMER P/N:

PRODUCT DIMENSIONS

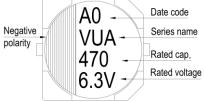


	Unit: mm
φD	8
L	10 ± 0.5
Α	8.3
В	8.3
С	9.0
W	0.7~1.1
Р	3.1 ± 0.2

Page: 1 / 1

Items				Р	erformance				
Rated Voltage V _R					25 V				
Capacitance C _R					220 µF		(120	Hz, 20°ℂ	
Category Temperature Range				-40°	~ +125°C	;			
Capacitance Tolerance		-20 % ~ +20 % (120 Hz, 20°C)							
Surge Voltage V _S					28.8 V _{DC}				
Leakage Current (20°C)				I _{LE}	_{AK} ≦ 165 μΑ		After	1 minute	
Tan δ		≤ 0.21 (120 Hz, 20							
Ripple Current (I _{AC, R} /rms)		130 mA (120 Hz, 1							
Low Temperature Characteristics at 120 Hz				$Z_{(-25^{\circ})} / Z_{(+25^{\circ})} / Z_{(+25^{\circ})} / Z_{(+25^{\circ})} / Z_{(+25^{\circ})} / Z_{(+25^{\circ})} / Z_{(+25^{\circ})}$		4 6			
Ripple Current (A) and	Frequency		y (Hz)	50	120	1k	10k up		
Frequency Multipliers		Multip	lier	0.80	1.00	1.25	1.40		
	Items		Endura	ınce		Shelf Life Test			
	Test Tin	ne	2,000 Hrs at 125°C; <i>V_R</i>			1,000 Hrs at 1	1,000 Hrs at 125℃		
Endurance and Shelf Life Test	Cap. Ch	nange	Within	±30 % of initial	value	Within ±30 %	of initial value		
1 001	Tan δ		Less th	an 300% of sp	ecified value	e Less than 300	Less than 300% of specified value		
	Leakage	e Current	Within	specified value	ı	Within specified value			
Standards				JIS C 5101	-1, -18, IEC	60384-4			
Remarks				RoHS Com	oliance, Hal	ogen-free			

Marking: Each capacitor shall be marked with the following information



_/	<u>0</u>	\rightarrow	January	, 2020	
			The suffi Month of		-
ſ					

Month	1	2	3	4	5	6
Code	Α	В	С	D	Е	F
Month	7	8	9	10	11	12
Code	G	Η	I	J	K	L

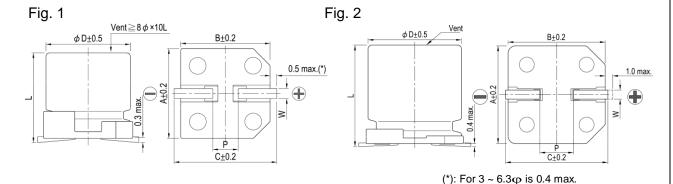
Marking color: Black

^{*} Please refer to "Precautions and Guidelines for Aluminum Electrolytic Capacitors" section in Lelon's catalog for further details.

Publication Date	March 14, 2020	Approval Signatures:	Approved	Checked	Designed
Revision Date			R & D	R & D	R & D
Version No.	1	Please return one copy with your approval	MAR. 16. 2020 Jack Huang	MAR. 16. 2020 H.Y.Huang	Z.X.Sun

Diagram of Dimensions:

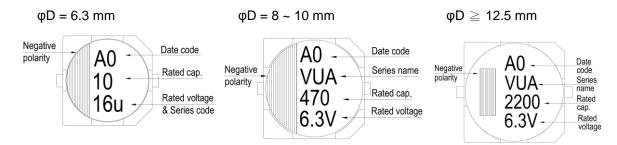
Unit: mm



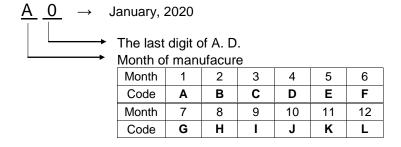
φD	L	Α	В	С	W	P ± 0.2	Fig. No.
6.3	5.7 ± 0.3	6.6	6.6	7.2	0.5 ~ 0.8	2.0	1
6.3	7.7 ± 0.3	6.6	6.6	7.2	0.5 ~ 0.8	2.0	1
8	6.5 ± 0.3	8.3	8.3	9.0	0.5 ~ 0.8	2.3	1
8	10 ± 0.5	8.3	8.3	9.0	0.7 ~ 1.1	3.1	1
10	10 ± 0.5	10.3	10.3	11.0	0.7 ~ 1.3	4.7	1
12.5	13.5 ± 0.5	13.0	13.0	13.7	1.1 ~ 1.4	4.4	2
12.5	16 ± 0.5	13.0	13.0	13.7	1.1 ~ 1.4	4.4	2
16	16.5 ± 0.5	17.0	17.0	18.0	1.1 ~ 1.4	6.4	2
18	16.5 ± 0.5	19.0	19.0	20.0	1.1 ~ 1.4	6.4	2

Marking:

Each capacitor shall be marked with the following information.



Description of Date Code:



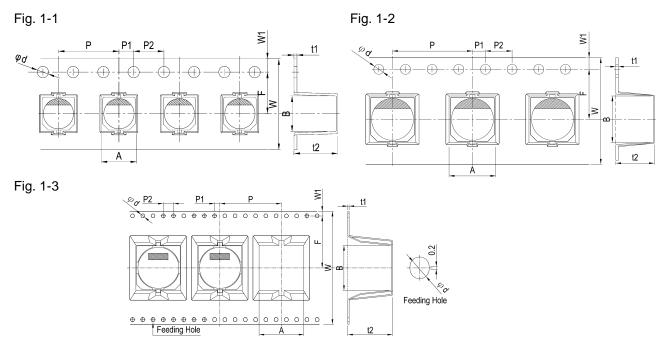
Origin code:

Huizhou: A0 , B0 , \dots , K0, L0 Suzhou: 0A , 0B , \dots , 0K , 0L

Marking Color: Black

Taping Specification for SMD Type

1. Carrier Tape



φD×L	А	В	φd	F	Р	P1	P2	t1	t2	W	W1	Unit: mm
3~4 ×4.5	4.5	4.5	Ψū	5.5	8		12		4.8	**	VV 1	
4 ×5.3	4.5	4.5		5.5	8				5.8			1-1
4 ×5.7	4.5	4.5		5.5	8				6.3	12.0		
5 ×4.5	5.5	5.5	-	5.5	12				4.8	_		
5 ×5.3	5.5	5.5		5.5	12				5.9			
5 ×5.7 ~ 5.8	5.5	5.5		5.5	12				6.3			
6.3 ×4.5	6.8	6.8	-	7.5	12			0.4	4.8			
6.3 ×5.3	6.8	6.8	-						5.9			
6.3 ×5.7 / 5.8	6.8	6.8	-	7.5	12				6.3	16.0		
6.3 ×7.7	6.8	6.8	-						8.3			
6.3 ×8.7	6.8	6.8	-						9.3			
6.3 ×9.5	6.8	6.8		11.5	16			0.5	10.6	24.0		1-2
8 ×6.5	8.7	8.7		7.5	12				6.9	16.0		
8 ×9.5~10									11.0			
8 ×10.5(G)	9.4	9.4		11.5	16				11.4	24.0		
10 ×7.7	10.7	10.7				2.0	4.0		8.7	-		
10 ×10			1.5						11.0		1.75	
10 ×10.5(G)	11.4	11.4							11.4			
10 ×12.5	10.7	10.7							13.1			
10 ×16.5	10.7	10.7							17.5			
12.5 ×13.5	13.4	13.4							14.5			
12.5 ×13.5(G)	13.7	13.7		14.2	24				15.0	32.0		
12.5 ×16	13.4	13.4							17.0			
12.5 ×16(G)	13.7	13.7						0.5	17.5			
16 ×16.5	17.5	17.5							17.0			1-3
16 ×16.5(G)	17.5	17.5			28				17.5	44.0		
16 ×21.5	17.5	17.5		20.2					23.0			
18 ×16.5	19.5	19.5			32				17.5			
18 ×16.5(G)	19.6	19.6			32				17.5			
18 ×21.5	19.5	19.5							23.0			
Tol.	± 0.2	± 0.2	+0.1/-0	± 0.1	± 0.1	± 0.1	± 0.1	± 0.1	± 0.2	± 0.3	± 0.15	

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2. Reel Package

Fig. 2-1

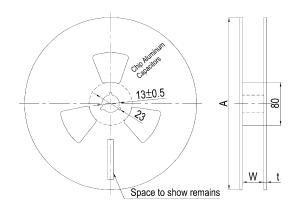
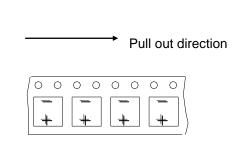
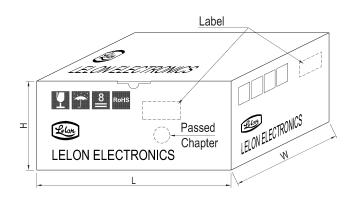


Fig. 2-2 Reel Polarity



Case size	3 ~ 4 <i>φ</i>	5ϕ	6.3ϕ	8 ¢ × 6.5	8 ¢ × 10	10ϕ	12.5ϕ	16 ~ 18 ¢
W	14	14	18	18	26	26	34	46
Α	380	380	380	380	380	380	380	380
t	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0

3. Packing specification Fig. 3-1 Carrier Tape



Unit: pcs

Case size	Q'ty / Reel	Q'ty / Box
3φ	2,000	20,000
4ϕ	2,000	20,000
5φ	1,000	10,000
6.3ϕ	1,000	10,000
8 φ × 6.5	1,000	10,000
8 φ ×10L	500	5,000
10 φ ×7.7 ~ 10L	500	5,000
10 φ ×12.5L	400	4,000
12.5 φ ×13.5L	200	1,600
12.5 ¢ ×16L	200	1,600
16 φ ×16.5L	200	1,600
16 φ ×21.5L	100	800
18 ¢ ×16.5L	150	1,200
18 <i>ф</i> ×21.5L	100	800

Unit: mm

(Case size	3 ~ 4 <i>φ</i>	5φ	6.3ϕ	$8\phi \times 6.5$	8 0 × 10	10 <i>ϕ</i>	12.5 ¢	16 ~ 18 φ
	Н	210	210	250	250	330	330	330	425
	W, L	395	395	395	395	395	395	395	395

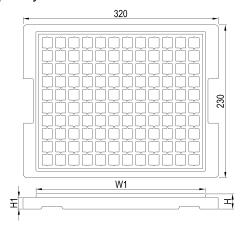
Ver. 12 -2-

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Fig. 3-2 Label



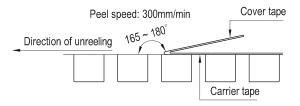
4. Chip Tray



Dimension and		Unit: mm			
Case size	W1	Н	H1	Q'ty / Tray	Q'ty / Box
12.5 φ ×13.5L	284	21	18.5	120	600
12.5 φ ×16L	284	21	18.5	120	600
16 φ ×16.5L	284	28	24.0	80	400
16 φ ×21.5L	284	28	24.0	80	400
18 <i>ф</i> ×16.5L	284	28	24.0	60	300
18 φ ×21.5L	284	28	24.0	60	300

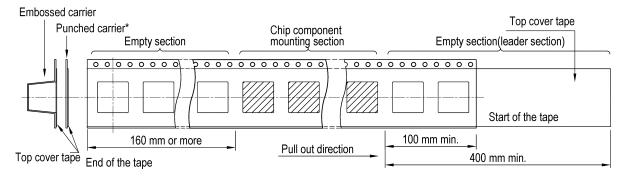
5. Sealing Tape Reel Strength

- 5.1 Peel angle: 165 to 180°C refered to the surface on which the tape is glued.
- 5.2 Peel speed: 300mm per minutes
- 5.3 The peel strength must be $0.1 \sim 0.7N$ under these conditions.



6. Packing Method

- 6.1 The leader length of the tape shall not be less than 400 mm including 10 or more embossed sections in which no parts are contained.
- 6.2 The winding core is provided with an over 160mm long empty section; punched carrier is only suitable for ϕ D \leq 5 mm.



7. Other: Specifications stated above is in accordance with JIS C 0806-3.

Ver. 12 -3-

Endurance characteristic:

No.	<u>urance cnaract</u> Item	Cond	itions						Specification		
1	Rotational	Capacitor is placed in an o		tempe	rature	Capa	acitance		•		
	Temperature Test	follow specific regulation to	•	•		chan	ige	VVILI	nin ± 10% of initial value		
		regulation is " +25°C (3 min	-		-	Tano		With	nin specified value		
		\rightarrow +25°C (3 min.) \rightarrow +125° min.) ", and it is called a cy	cle. The te	st totals	s 10	Leak	ent	With	nin specified value		
		cycles, and then the capac standard atmospheric con- which measurements shall	ditions for 4 I be made.	hours,		Phys			proken and undamaged		
2	High Temperature Endurance Life	 Capacitors shall be place application of rated volta 		with		Capa	acitance ige	With	nin ± 30% of initial value		
	Test	1,000 +48 / -0 hours for	$\phi D \leq 6.3$	~8×6	.5 mm;	Tanō	5	Les	s than 300% of specified value		
		$2,000 +72 / -0$ hours for 125° C.	10 ~ 18	Leak Curr		With	nin specified value				
		2. Then the capacitor shall atmospheric conditions measurements shall be	for 4 hours made.	, after v	vhich	Phys	sical	No t	oroken and undamaged		
3	High Temperature Unload Life Test	After 1,000 +48 / -0 Hours rated voltage. And then the				Capa chan	acitance ige	With	nin ± 30% of initial value		
		subjected to standard atmo	ospheric co	ndition	s for	Tano	5	Les	s than 300% of specified value		
		4 hours, after which measu	urements s	nall be	made.	Leak Curr		With	nin specified value		
						Phys			proken and undamaged		
4	Humidity Test	Capacitors shall be expose in an atmosphere of 90 ~ 9			-0 hours	Capa chan	acitance ige	With	Within ± 10% of initial value		
		3℃.							s than 120% of specified value		
			nd then the capacitor shall be subjected to andard atmospheric conditions for 4 hours, after						nin specified value		
		which measurements shall				Phys	sical	No l	proken and undamaged		
5	Low Temperature Test	Capacitors are placed at -4 And then the capacitor sha			hours.	Capa chan	acitance ige	With	nin ± 10% of initial value		
		standard atmospheric cond		hours,	after	Tano		With	Within specified value		
		which measurements shall	l be made.			Leak Curr		With	Within specified value		
						Phys			No broken and undamaged		
6	Vibration Test	1. Fix it at the point 4 mm ones of 12.5 mm or more	e in diamet			chan		VVILI	Within ± 10% of initial value		
		more length, use separa				Tano		With	Within specified value		
		 Direction and during of v 3 orthogonal directions r 		ch for 2	hours	Leak	ent		nin specified value		
		(total of 6 hours). 3. Frequency:				Phys	sical	No I	proken and undamaged		
		10 to 55 Hz reciprocation 4. Total amplitude: 1.5 mm	1								
7	Surge Voltage Test	The capacitor shall be sub 15 ~ 35°C. Protective series				Capa chan	acitance ige	With	nin ± 20% of initial value		
		consisting of a charge peri				Tano		Les	s than 175% of specified value		
		followed by discharge periodinutes.	od of appro	ximate	y 5.5	Leak Curr		With	nin specified value		
		Applying voltage:				Phys	sical	No l	proken and undamaged		
		Rated Voltage(V) 1	10 16	25	35	50	63	400			
			1.5 18.4	28.8		57.5	72.5	440			
			,								

LELON ELECTRONICS CORP. VUA-APR-12

specified clearly in the next item. fixated on.	tion			
Tan Within specified Current Time(sec) Rated voltage (V) 10 - 35 10 - 63 Case size (φ) 3 - 6.3 8 - 18 Temp. (T1 - T2, C) 150 - 180 Time (t1) Time (t2) (max, secs) 90 60 60 40 Paak Temp. (T4, C) 260 250 Reflow cycles 2 or less 2. Solder iron method: Bit temperature: 350 ± 5°C Application time of soldering Iron: 3 + 1 / -0 sec * Please contact our representative if your condition is higher. * Please ensure that the capacitor became cold enough to the room temperature (5°C - 35°C) before the second reflow. * Consult with us when performing reflow profile in IPC / JEDEC (J-STD-020) Bending Test: Apply pressure in the direction of the arrow at a rate of about 0.5 mm / s until bent width reaches 2 mm and hold for 60s. The board shall be the test board 'B' as specified in JIS C 0051: 2002. If the land area differs, it shall be specified clearly in the next item. 10 Solderability After the lead wire fully immersed in the solder for 2 ± 0.5 secs at a temperature of 245 ± 5°C)% of initial \	value		
Leakage Current No broken and Time (sec) Rated voltage (V) 10 - 35 10 - 63 Case size (Ø) 3 - 6.3 8 - 18 Temp. Preheat Time (t1) 100 Time (t2) 100 Time (t2) 260 250 Time (t3) 20 217 230 217 230 Peak Temp. (T4, °C) 260 250 Reflow cycles 2 or less 2. Solder iron method: Bit temperature: 350 ± 5°C Application time of soldering Iron: 3 + 1 / -0 sec *Please contact our representative if your condition is higher. *Please ensure that the capacitor became cold enough to the room temperature (5°C - 35°C) before the second reflow. *Consult with us when performing reflow profile in IPC / JEDEC (J-STD-020) Bending Test: Characteristics Test Mithout mechanical damage: breaks. Electrical characterists satisfied. If there are electrod sour days above requirements satisfied on whichever surface final satisfied o				
Time(sec) Rated voltage (V) 10 - 35 10 - 63 Case size (\$\phi\$) 3 - 6.3 8 - 18 Temp. Preheat Temp. (T1, T2, \text{\$\text{\$\text{\$V\$}}\$} 150 - 180 Time (11) 100 Duration Time (12) 100 Time (12) 90 60 60 40 Time (13) 255 Reflow cycles 2 or less 2. Solder iron method: Bit temperature: 350 ± 5°C Application time of soldering Iron: 3 + 1 / -0 sec * Please contact our representative if your condition is higher. * Please ensure that the capacitor became cold enough to the room temperature (5°C - 35°C) before the second reflow. * Consult with us when performing reflow profile in IPC / JEDEC (J-STD-020) Bending Test: Characteristics Test Apply pressure in the direction of the arrow at a rate of about 0.5 mm / s until bent width reaches 2 mm and hold for 60s. The board shall be the test board "B" as specified in JIS C 0051: 2002. If the land area differs, it shall be specified clearly in the next item. Without mechanical damage: breaks. Electrical characterist satisfied on whichever surface on whichever surface in JIS C 0051: 2002. If the land area differs, it shall be specified clearly in the next item. After the lead wire fully immersed in the solder for 2 ± 0.5 secs at a temperature of 245 ± 5°C After the lead wire fully immersed in the solder for 2 ± 0.5 secs at a temperature of 245 ± 5°C				
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	ength = actual width of substrate + on both sides	+ 5 (minimum) s		
Test solder coating must be more than 95%.	. 5 (), trie so 	,,uerthe		
11 Venting Test 1. Applicable to the capacitors with case size is 8×10 mm and larger. 2. Test condition:				
(1) AC test: The capacitor shall be connected across an applying 50 or 60 Hz AC which is	h is 0.7 time	es of		
rated voltage or 250Vrms AC whichever is the lower.				
(2) DC test: Applying inverse DC rated voltage with current to the capacitor. Where case diameter: φ D ≤ 22.4 mm: 1 A DC max.				
ϕ D $>$ 22.4 mm: 10 A DC max.				
Note: (1) When the pressure relief vent operated, the capacitor shall avoid any danger of fire or	a or evaloric	on of		
capacitor element(terminal and metal foil etc.) or cover.	or exhinain	JII OI		
(2) When the pressure relief device does not open with the voltage applied over 30 minute	nutes, the te	est is		
considered to be passed.				

LELON ELECTRONICS CORP. VUA-APR-12

No.	Item	Conditions						
12	Land Pattern	Recommended pad pattern and size						
		Case size Land size Case size Land size						
		G Y X						
		5ϕ 1.4 3.0 1.6 10 ϕ 4.0 4.0 2.5						
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$						
		$8\phi \times 6.5$ L 2.1 4.0 1.6 16ϕ 6.0 7.0 3.2						
		8ϕ 3.0 3.5 2.5 18ϕ 6.0 8.0 3.2						
		C						
13	Standards	Satisfies Characteristic JIS C 5101-1, -18						

LELON ELECTRONICS CORP. VUA-APR-12

Precautions and Guidelines for Aluminum Electrolytic Capacitors

1. Guidelines for Circuit Design (General / Application guidelines for using electrolytic capacitors)

Selecting of a right capacitor is a key to a good circuit design.

(1) Polarity

Most of the aluminum electrolytic capacitors are polarized. Therefore, they must be installed with the correct polarity. Usage in the reverse polarity results into a short-circuit condition that may damage or even explode the capacitor. In addition, it may influence circuit functionality. A bi-polar electrolytic capacitor should be installed when polarity across a capacitor is unstable / reversible. It should be, however, noted that usage of both polar and bi-polar capacitors are limited to DC applications. They must NOT be used for AC application.

(2) Operating Voltage
Applied DC voltage must not exceed rated voltage of the capacitor. Applying higher voltage than its rated voltage across a capacitor terminals cause overheating due to higher leakage currents and capacitor dielectric/insulation deterioration that will ultimately affect a capacitor's performance. The device, however, is capable of working under short-time transient voltages such as DC transients and peak AC ripples. Reverse voltages higher than 1 Volt within a specified temperature limit or AC voltages are not permissible. Overall, using capacitors at recommended operating voltages can prolong its lifespan. Note that the result of DC voltage overlapped with peak ripple voltage should not exceed rated voltage.

(3) Ripple Current

One of the key functions of any capacitor is removal of the ripple current i.e. the RMS value of AC flowing through a capacitor. But, a ripple current higher than rated ripple current will drop resultant capacitance, cause undue internal heating and thus reduces life span of the capacitor. In extreme cases, internal high temperature will cause the pressure relief vent to operate while destroying the device. Overall, it is important to note that an electrolytic capacitor must be used within a permissible range of ripple current. Indicators like temperature coefficient of allowable ripple current are generally used to determine life expectancy of the capacitor, but to avoid related complex calculations and for the sake of simplicity, we haven't provided temperature coefficient in the catalogue. But it offers key indicators like maximum operating temperature for calculation of life expectancy at a given temperature.

(4) Operating Temperature

Capacitors should be used within a permissible range of operating temperatures. Using capacitor at a higher temperature than maximum rated temperature will considerably shorten its life. In the worst-case scenario, high temperature can cause pressure relief vent to operate and the device will get destroyed. Using capacitors at an ambient room temperature assure their longer life.

(5) Leakage Current

Leakage current flows through a capacitor when DC voltage is applied across it. Leakage current varies with changes in ambient temperature and applied DC voltage level and its time of application. Overvoltage situation, presence of moisture, and thermal stresses, especially occurring during the soldering process can enhance leakage current. Initial leakage current is usually higher and does not decrease until voltage is applied for a certain period of time. It is recommended to keep initial leakage current within specified levels.

(6) Charge and Discharge

Regular electrolytic capacitors are not suitable for rapid charging/discharging circuits. Such usage may either cause reduction in overall capacitance or damage due to overheating. Lelon provides special assistance for selecting appropriate capacitors for rapid charging/discharging circuits.

(7) Surge Voltage

The Surge voltage rating is referred as the maximum DC overvoltage that may be applied to an electrolytic capacitor for a short time interval of 30 seconds at infrequent time intervals not exceeding 5.5minutes with a limiting resistance of $1k\Omega$. Unless otherwise described on the catalogue or product specifications, please do not apply a voltage exceeding the capacitor's voltage rating. The rated surge voltages corresponding to rated voltages of electrolytic capacitors are presented as follows:

Rated Voltage(V)	4	6.3	10	16	25	35	50
Surge Voltage(V)	4.6	7.3	11.5	18.4	28.8	40.3	57.5
	I					I	
Rated Voltage(V)	63	80	100	160	200	250	315
Surge Voltage(V)	72.5	92	115	184	230	288	347
	r	Ι	Ι	Ι	Ι	r	1
Rated Voltage(V)	350	400	420	450	500	525	
Surge Voltage(V)	385	440	462	495	550	578	

(8) Condition of Use

The capacitors shall NOT be exposed to:

- (a) Fluids including water, saltwater spray, oil, fumes, highly humid or condensed climates, etc.
- (b) Ambient conditions containing hazardous gases/fumes like hydrogen sulfide, sulfurous acid, nitrous acid, chlorine or bromine gas, ammonia, etc.
- (c) Exposed to ozone, ultraviolet rays and radiation.
- (d) Severe vibrations or physical shocks that exceeds the specifications mentioned in this catalogue.

(9) Circuit Design Consideration

- (a) Please ensure whether application, operating and mounting conditions satisfy the conditions specified in the catalog before installation of a capacitor. Please consult Lelon, if any of the conditions are beyond the conditions specified in the catalog.
- (b) Heat-generating components or heat sinks should not be placed closer to Aluminum electrolytic capacitors on the PCB to avoid their premature failure. A cooling system is recommended to improve their reliable working.
- (c) Electrical characteristics and performance of aluminum electrolytic capacitors are affected by variation of applied voltage, ripple current, ripple frequency and operating temperature. Therefore, these parameters shall not exceed specified values in the catalog.
- (d) Aluminum capacitors may be connected in the parallel fashion for increasing total capacitance and/or for achieving higher ripple current capability. But, such design may cause unequal current flow through each of the capacitors due to differences in their impedances.
- (e) When two or more capacitors are connected in series, voltage across each capacitor may differ and fall below the applied voltage. A resistor should be placed across each capacitor so as to match applied voltage with voltage across a capacitor.
- Please consult Lelon while selecting a capacitor for highfrequency switching circuit or a circuit that undergoes rapid charging/ discharging
- (g) Standard outer sleeve of the capacitor is not a perfect electrical insulator therefore is unsuitable for the applications that requires perfect electrical insulation. Please consult Lelon, if your application requires perfect electrical insulation.
- (h) Tilting or twisting capacitor body is not recommended once it is soldered to the PCB.

2. Caution for Assembling Capacitors

(1) Mounting

(a) Aluminum electrolytic capacitors are not recommended to reuse in other circuits once they are mounted and powered in a circuit.

- (b) Aluminum electrolytic capacitors may hold static charge between its anode and cathode, which is recommended to be discharged through a 1kΩ resistor before re-use.
- (c) A long storage of capacitors may result into its insulation deterioration. This can lead to a high leakage current when voltage is applied that may damage the capacitor. Capacitors following a long storage period must undergo voltage treatment/re-forming.

Capacitors are charged by applying rated DC voltage through a resistor of $1k\Omega$ in series at least for an hour. It is recommended to increase applied voltage gradually using a voltage regulator unit once capacitors are assembled on the board. The charging should be followed by discharging through a $1K\Omega$ resistor.

- (d) Please check capacitor rated voltage before mounting.
- (e) Please check capacitor polarity before mounting.
- (f) Please don't drop capacitor on the floor / hard object.
- (g) Please don't deform the capacitor during installation.
- (h) Please confirm whether the lead spacing of the capacitors match with its pad spacing / footprint on PCB prior to installation.
- Please avoid excessive mechanical shocks to capacitor during the auto-insertion process, inspection or centering operations.
- (j) Please don't place any wiring or circuit over the capacitor's pressure relief vent. The pressure relief vent may fail to open if adequate clearance space is not provided. Following table shows minimum clearance space required for different case diameters.

Case Diameter	φ6.3 ~ φ16	φ 18 ~ φ 35	ϕ 40 or above
Clearance (min)	2 mm	3 mm	5 mm

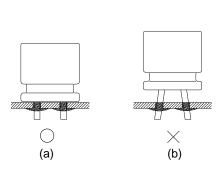
(2) Soldering

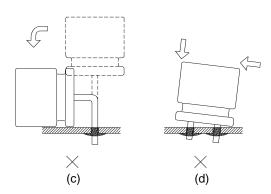
- (a) Please confirm that soldering conditions, especially temperature and contact time are within our specifications. Dip or flow soldering temperature should be limited at 260 ± 5°C for 10 ± 1 sec while manual soldering using soldering iron should be limited at 350 ± 5°C for 3 +1/-0 seconds. Please do not dip capacitor body into molten solder. A capacitor's life will be negatively affected if these conditions are violated.
- (b) Storage of capacitors in *high humidity* conditions is likely to *affect* the *solder-ability of lead wires and terminals*.

- (c) Reflow soldering should NOLY be used for SMD type capacitors. The temperature and duration shall not exceed the specified temperature and duration in the specification. If the temperature or duration is higher than the value specified, please consult Lelon before usage.
- (d) Standard aluminum electrolytic capacitors are not designed to withstand multiple reflow processes. Please consult Lelon if repeated reflowing is unavoidable.
- (e) Incorrect mounting on PCB with improper external strength applied on its lead wires or capacitor body after soldering may damage a capacitor's internal structure, cause short circuit, or lead to high leakage current issues. Do not bend or twist the capacitor body after soldering. Referring to the drawings below only case (i) is recommended.
 - (i) Correct soldering
 - (ii) Hole-to-hole spacing on PCB differs from the lead space of lead wires.
 - (iii) Lead wires are bent after soldering.
 - (iv) Capacitor body doesn't stand vertical on PCB after soldering.

(3) Cleaning Circuit Boards after Soldering

- (a) Following chemicals are not recommended for cleaning: Solvent containing halogen ions, Alkaline solvent, Xylene, Acetone, Terpene, petro-based solvent.
- (b) Recommended cleaning conditions: Fatty-alcohol - Pine Alpha ST-100S, Clean Through-750H and IPA (isopropyl alcohol) are examples of the most acceptable cleaning agents. Temperature of the cleaning agent must not exceed 60°C. Flux content in the cleaning agents should be limited to 2 Wt. %. Overall length of cleaning process (e.g., immersion, ultrasonic or other) shall be within 5 minutes (5 -7mm height within 3 minutes). CFC substitute cleaning agents such as AK225AES can also be used for cleaning. In this case, its temperature shall not exceed 40 C and cleaning process (e.g., immersion, ultrasonic or other) shall be completed within 2 ~ 3 minutes. After cleaning capacitors should be dried with hot air for at least 10 minutes along with the PCB. Temperature of hot air shall not exceed maximum category temperature of the capacitor. Insufficient drying may cause appearance defects, sleeve shrinkage, and bottom-plate bulging. However, usage of this CFC substitute must completely regulated for protection of environment.





3. Maintenance Inspection

Periodical inspection of aluminum capacitors is absolutely necessary, especially when they are used with industrial equipment. The following items should be checked:

- (1) Appearance: Bloated, vent operated, leaked, etc.
- (2) Electrical characteristic: Capacitance, Tanδ, leakage current, and other specified items listed in specification.

Lelon recommend replacing the capacitors if any of the abovementioned items fail to meet specifications.

4. Storage

- (1) The most suitable conditions for aluminum capacitor storage are 5 °C ~ 35°C and indoor relative humidity less than 75%. High temperature and/or humidity storage is detrimental to the capacitors.
- (2) Capacitors shall not be stored in wet or damp atmospheres containing water, brine, fumes or oil.
- (3) Capacitors storage area shall neither be exposed to hazardous gases such as hydrogen sulfide, sulfurous acid, nitrous acid, chlorine, ammonium, etc. nor to acidic or alkaline solutions.
- (4) Capacitors shall not be exposed to ozone, ultraviolet rays or radiation.

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5. Estimation of life time

 $L_r = L_0 \times 2^{\frac{T_{0\text{max}} - T_{r\text{max}}}{10}}$

Lr: Estimated lifetime (hours)

L₀: Base lifetime specified at maximum operating temperature with applied the DC voltage and the ripple current (hours)

 $T_{0\,\text{max}}$: The core temperature that rated ripple current applied at maximum operating temperature.

 $T_{r\,\text{max}}$. The core temperature that applied actual ripple current at ambient temperature.

6. Disposal

Please consult with a local industrial waste disposal specialist when disposing of aluminum electrolytic capacitors.

7. Environmental Consideration

Lelon already have received ISO 14000 certificate. Cadmium (Cd), Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr⁺⁶), PBB, PBDE, DEHP, BBP, DBP and DIBP have never been using in capacitor. If you need "Halogen-free" products, please consult with us.

8. AEC-Q200 Compliance

Automotive Electronics Counsel (AEC) has established various electronic component qualification/reliability standards in order to serve automotive electronics industry. AEC-Q200 standard is dedicated for passive components like capacitors, inductors, etc. and is widely adopted domestically as well as internationally. Lelon offers compliant product designs and support services to satisfy customers' product requirements, including the AEC-Q200 required criteria of the reliability tests. Lelon's capacitors are professionally designed to outperform all requirements of AEC-Q200.

For further details, please refer to

IEC 60384-4- Fixed capacitors for use in electronic equipment – Part 4: Sectional specification – Aluminium electrolytic capacitors with solid (MnO₂) and non-solid electrolyte (Established in January 1995, Revised in March 2007), and

EIAJ RCR-2367B- Guideline of notabilia for fixed aluminium electrolytic capacitors for use in electronic equipment [Technical Standardization Committee on Passive Components (Established in March 1995, Revised in March 2002)].

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